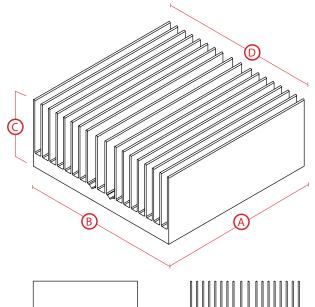


# **High Performance BGA Cooling Solutions w/ Thermal Tape Attachment**

# ATS PART # ATS-54210K-C2-R0

### **Features & Benefits**

- High aspect ratio, straight fin heat sinks that are ideal for » compact PCB environments
- Designed specifically for BGAs and other surface mount » packages
- Comes preassembled with high performance thermal » interface material



\*Image above is for illustration purposes only.



#### **Thermal Performance**

AIR VELOCITY			THERMAL RESISTANCE		
FT/MIN	Μ	I/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)	
200	1	.0	11.1	7.1	
300	1	.5	9		
400	2	.0	7.8		
500	2	.5	7		
600	3	.0	6.4		
700	3	.5	6		
800	4	.0	5.6		
	FT/MIN 200 300 400 500 600 700	FT/MIN M   200 1   300 1   400 2   500 2   600 3   700 3	FT/MINM/S2001.03001.54002.05002.56003.07003.5	FT/MINM/S°C/W (UNDUCTED FLOW)2001.011.13001.594002.07.85002.576003.06.47003.56	

## **Product Details**

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
21 mm	21 mm	14.5 mm	21 mm	SAINT-GOBAIN C675	BLACK-ANODIZED

#### **NOTES:**

Dimension C = heat sink height from bottom of the base to the top of the fin field.

2) Thermal performance data are provided for reference only. Actual performance may vary

by application.

ATS reserves the right to update or change its products without notice to improve the 3) design or performance.

4) Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.gats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).